

- Easily Interfaced to Microprocessors
- On-Chip Data Latches
- Monotonic Over the Entire A/D Conversion Range
- Interchangeable With Analog Devices AD7528 and PMI PM-7528
- Fast Control Signaling for Digital Signal Processor (DSP) Applications Including Interface With TMS320
- Voltage-Mode Operation
- CMOS Technology

KEY PERFORMANCE SPECIFICATIONS	
Resolution	8 bits
Linearity Error	1/2LSB
Power Dissipation at $V_{DD} = 5V$	20mW
Settling Time at $V_{DD} = 5V$	100ns
Propagation Delay Time at $V_{DD} = 5V$	80ns

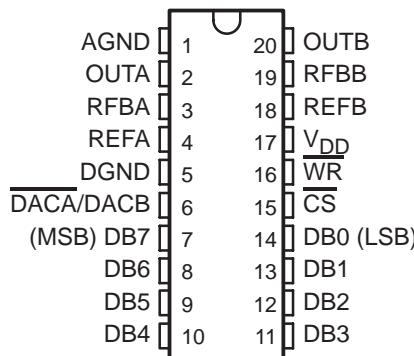
## description

The TLC7528C, TLC7528E, and TLC7528I are dual, 8-bit, digital-to-analog converters (DACs) designed with separate on-chip data latches and feature exceptionally close DAC-to-DAC matching. Data are transferred to either of the two DAC data latches through a common, 8-bit, input port. Control input DACA/DACB determines which DAC is to be loaded. The load cycle of these devices is similar to the write cycle of a random-access memory, allowing easy interface to most popular microprocessor buses and output ports. Segmenting the high-order bits minimizes glitches during changes in the most significant bits, where glitch impulse is typically the strongest.

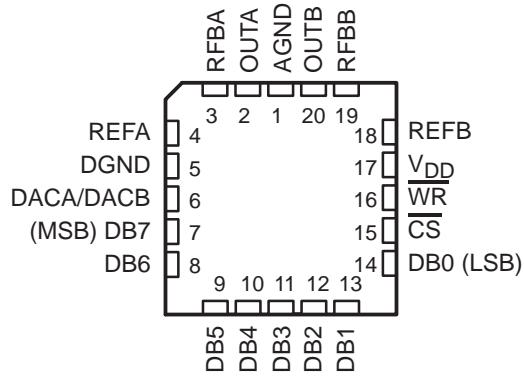
These devices operate from a 5V to 15V power supply and dissipates less than 15mW (typical). The 2- or 4-quadrant multiplying makes these devices a sound choice for many microprocessor-controlled gain-setting and signal-control applications. It can be operated in voltage mode, which produces a voltage output rather than a current output. Refer to the typical application information in this data sheet.

The TLC7528C is characterized for operation from 0°C to +70°C. The TLC7528I is characterized for operation from -25°C to +85°C. The TLC7528E is characterized for operation from -40°C to +85°C.

DW, N OR PW PACKAGE  
(TOP VIEW)



FN PACKAGE  
(TOP VIEW)



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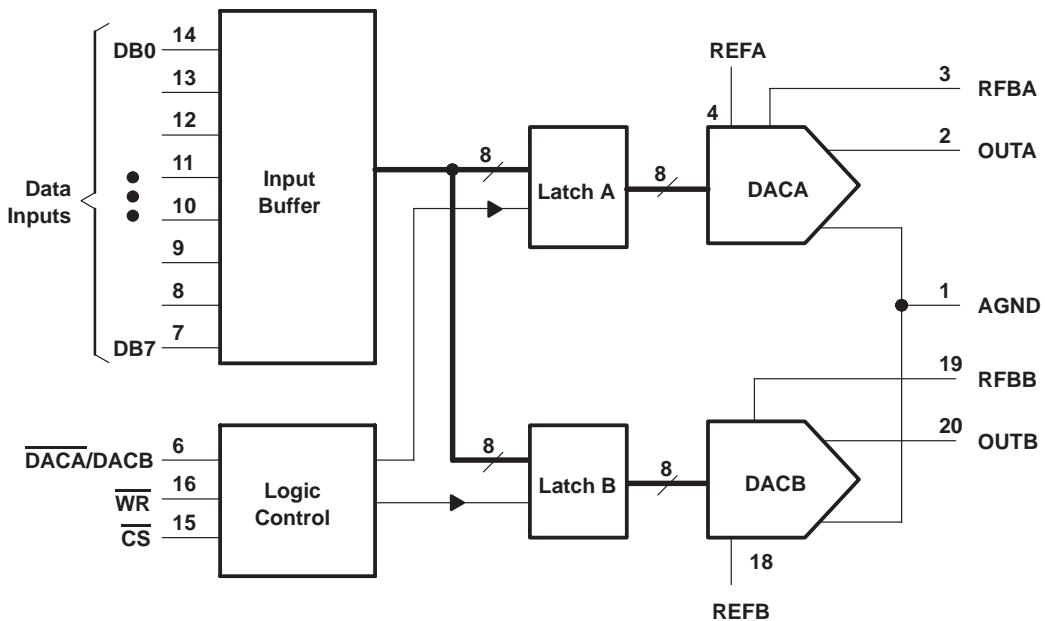
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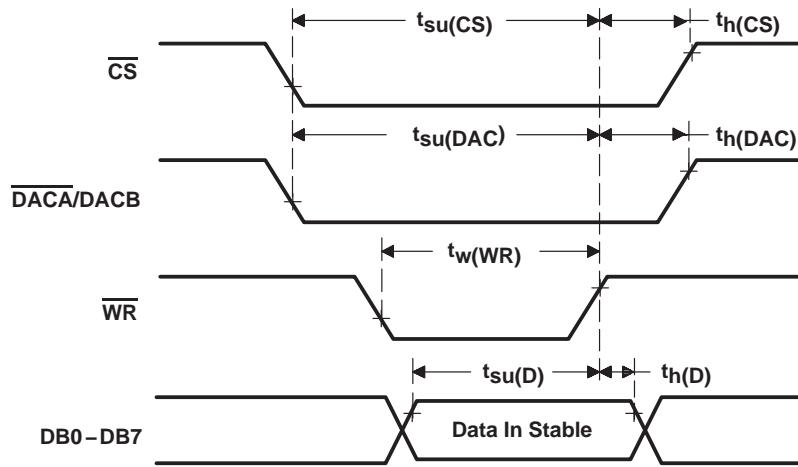
**TLC7528C, TLC7528E, TLC7528I  
DUAL 8-BIT MULTIPLYING  
DIGITAL-TO-ANALOG CONVERTERS**

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**functional block diagram**



**operating sequence**



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**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{DD}$ (to AGND or DGND)	.....	.....	.....	-0.3V to 16.5V
Voltage between AGND and DGND	.....	.....	.....	$\pm V_{DD}$
Input voltage range, $V_I$ (to DGND)	.....	.....	.....	-0.3V to $V_{DD} + 0.3$
Reference voltage, $V_{refA}$ or $V_{refB}$ (to AGND)	.....	.....	.....	$\pm 25V$
Feedback voltage $V_{RFBA}$ or $V_{RFBB}$ (to AGND)	.....	.....	.....	$\pm 25V$
Input voltage (voltage mode out A, out B to AGND)	.....	.....	.....	-0.3V to $V_{DD} + 0.3$
Output voltage, $V_{OA}$ or $V_{OB}$ (to AGND)	.....	.....	.....	$\pm 25V$
Peak input current	.....	.....	.....	$10\mu A$
Operating free-air temperature range, $T_A$ :	TLC7528C	.....	.....	0°C to +70°C
	TLC7528I	.....	.....	-25°C to +85°C
	TLC7528E	.....	.....	-40°C to +85°C
Storage temperature range, $T_{stg}$	.....	.....	.....	-65°C to +150°C
Case temperature for 10 seconds, $T_C$ : FN package	.....	.....	.....	+260°C
Lead temperature 1,6mm (1/16 inch) from case for 10 seconds: DW or N package	.....	.....	.....	+260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

**package/ordering information**

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).

**recommended operating conditions**

		$V_{DD} = 4.75V$ to $5.25V$			$V_{DD} = 14.5V$ to $15.5V$			<b>UNIT</b>	
		MIN	NOM	MAX	MIN	NOM	MAX		
Reference voltage, $V_{refA}$ or $V_{refB}$		.....	.....	.....	.....	.....	.....	V	
High-level input voltage, $V_{IH}$		.....	.....	.....	2.4	.....	13.5	V	
Low-level input voltage, $V_{IL}$		.....	.....	.....	.....	0.8	.....	1.5	V
CS setup time, $t_{su}(CS)$		.....	.....	.....	50	.....	50	ns	
CS hold time, $t_h(CS)$		.....	.....	.....	0	.....	0	ns	
DAC select setup time, $t_{su}(DAC)$		.....	.....	.....	50	.....	50	ns	
DAC select hold time, $t_h(DAC)$		.....	.....	.....	10	.....	10	ns	
Data bus input setup time $t_{su}(D)$		.....	.....	.....	25	.....	25	ns	
Data bus input hold time $t_h(D)$		.....	.....	.....	10	.....	10	ns	
Pulse duration, WR low, $t_w(WR)$		.....	.....	.....	50	.....	50	ns	
Operating free-air temperature, $T_A$	TLC7628C	0	.....	.....	0	.....	.....	°C	
	TLC7628I	.....	.....	.....	-25	.....	.....		
	TLC7628E	.....	.....	.....	-40	.....	.....		

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**electrical characteristics over recommended operating free-air temperature range,  
 $V_{refA} = V_{refB} = 10V$ ,  $V_{OA}$  and  $V_{OB}$  at 0V (unless otherwise noted)**

PARAMETER		TEST CONDITIONS	$V_{DD} = 5V$			$V_{DD} = 15V$			UNIT	
			MIN	TYP†	MAX	MIN	TYP†	MAX		
$I_{IH}$	High-level input current	$V_I = V_{DD}$			10			10	$\mu A$	
$I_{IL}$	Low-level input current	$V_I = 0$	5	12	-10	5	12	-10	$\mu A$	
Reference input impedance REFA or REFB to AGND					20			20	$k\Omega$	
$I_{Ikg}$	Output leakage current	OUTA	DAC data latch loaded with 00000000, $V_{refA} = \pm 10V$		±400			±200	$nA$	
		OUTB	DAC data latch loaded with 00000000, $V_{refB} = \pm 10V$		±400			±200		
Input resistance match (REFA to REFB)					±1%			±1%		
DC supply sensitivity, $\Delta$ gain/ $\Delta V_{DD}$		$\Delta V_{DD} = \pm 10\%$			0.04			0.02	%/%	
$I_{DD}$	Supply current (quiescent)	All digital inputs at $V_{IH}$ min or $V_{IL}$ max			2			2	$mA$	
$I_{DD}$	Supply current (standby)	All digital inputs at 0V or $V_{DD}$			0.5			0.5	$mA$	
$C_i$	Input capacitance	DB0–DB7			10			10	$pF$	
		WR, CS, DACA/DACB			15			15	$pF$	
$C_o$	Output capacitance (OUTA, OUTB)	DAC data latches loaded with 00000000			50			50	$pF$	
		DAC data latches loaded with 11111111			120			120		

† All typical values are at  $T_A = +25^\circ C$ .



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operating characteristics over recommended operating free-air temperature range,  
 $V_{refA} = V_{refB} = 10V$ ,  $V_{OA}$  and  $V_{OB}$  at 0V (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{DD} = 5V$			$V_{DD} = 15V$			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
Linearity error				$\pm 1/2$			$\pm 1/2$	LSB
Settling time (to 1/2LSB)	See Note 1			100			100	ns
Gain error	See Note 2			2.5			2.5	LSB
AC feedthrough	REFA to OUTA			-65			-65	dB
	REFB to OUTB	See Note 3		-65			-65	
Temperature coefficient of gain	See Note 4			0.007			0.0035	%FSR/ $^{\circ}$ C
Propagation delay (from digital input to 90% of final analog output current)	See Note 5			80			80	ns
Channel-to-channel isolation	REFA to OUTB	See Note 6		77			77	dB
	REFB to OUTA	See Note 7		77			77	
Digital-to-analog glitch impulse area	Measured for code transition from 00000000 to 11111111, $T_A = +25^{\circ}$ C			160			440	nV-s
Digital crosstalk	Measured for code transition from 00000000 to 11111111, $T_A = +25^{\circ}$ C			30			60	nV-s
Harmonic distortion	$V_i = 6V$ , $f = 1kHz$ , $T_A = +25^{\circ}$ C			-85			-85	dB

- NOTES:
- OUTA, OUTB load =  $100\Omega$ ,  $C_{ext} = 13pF$ ; WR and CS at 0V; DB0–DB7 at 0V to  $V_{DD}$  or  $V_{DD}$  to 0V.
  - Gain error is measured using an internal feedback resistor. Nominal full scale range (FSR) =  $V_{ref} - 1LSB$ .
  - $V_{ref} = 20V$  peak-to-peak, 100kHz sine wave; DAC data latches loaded with 00000000.
  - Temperature coefficient of gain measured from  $0^{\circ}$ C to  $+25^{\circ}$ C or from  $+25^{\circ}$ C to  $+70^{\circ}$ C.
  - $V_{refA} = V_{refB} = 10V$ ; OUTA/OUTB load =  $100\Omega$ ,  $C_{ext} = 13pF$ ; WR and CS at 0V; DB0–DB7 at 0V to  $V_{DD}$  or  $V_{DD}$  to 0V.
  - Both DAC latches loaded with 11111111;  $V_{refA} = 20V$  peak-to-peak, 100kHz sine wave;  $V_{refB} = 0$ ;  $T_A = +25^{\circ}$ C.
  - Both DAC latches loaded with 11111111;  $V_{refB} = 20V$  peak-to-peak, 100kHz sine wave;  $V_{refA} = 0$ ;  $T_A = +25^{\circ}$ C.

## PRINCIPLES OF OPERATION

These devices contain two identical, 8-bit-multiplying DACs, DACA and DACB. Each DAC consists of an inverted R-2R ladder, analog switches, and input data latches. Binary-weighted currents are switched between DAC output and AGND, thus maintaining a constant current in each ladder leg independent of the switch state. Most applications require only the addition of an external operational amplifier and voltage reference. A simplified DAC circuit for DACA with all digital inputs low is shown in Figure 1.

Figure 2 shows the DACA equivalent circuit. A similar equivalent circuit can be drawn for DACB. Both DACs share the analog ground terminal 1 (AGND). With all digital inputs high, the entire reference current flows to OUTA. A small leakage current ( $I_{lkq}$ ) flows across internal junctions, and as with most semiconductor devices, doubles every  $10^{\circ}$ C.  $C_o$  is due to the parallel combination of the NMOS switches and has a value that depends on the number of switches connected to the output. The range of  $C_o$  is 50pF to 120pF maximum. The equivalent output resistance ( $r_o$ ) varies with the input code from  $0.8R$  to  $3R$  where  $R$  is the nominal value of the ladder resistor in the R-2R network.

These devices interface to a microprocessor through the data bus, CS, WR, and DACA/DACB control signals. When CS and WR are both low, the TLC7528 analog output, specified by the DACA/DACB control line, responds to the activity on the DB0–DB7 data bus inputs. In this mode, the input latches are transparent and input data directly affects the analog output. When either the CS signal or WR signal goes high, the data on the DB0–DB7 inputs are latched until the CS and WR signals go low again. When CS is high, the data inputs are disabled regardless of the state of the WR signal.

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## PRINCIPLES OF OPERATION

The digital inputs of these devices provide TTL compatibility when operated from a supply voltage of 5V. These devices can operate with any supply voltage in the range from 5V to 15V; however, input logic levels are not TTL-compatible above 5V.

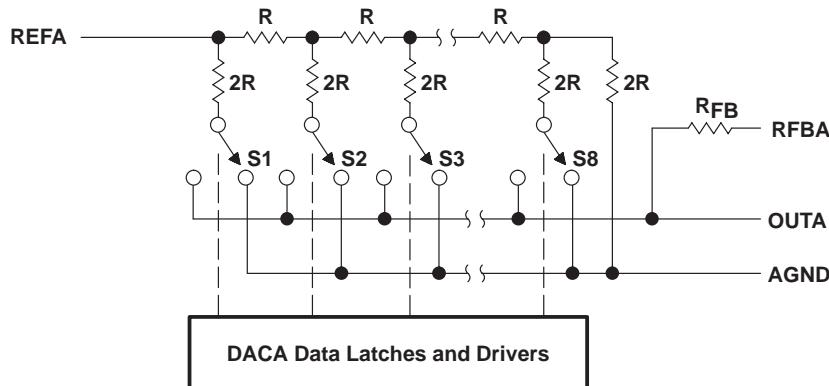


Figure 1. Simplified Functional Circuit for DACA

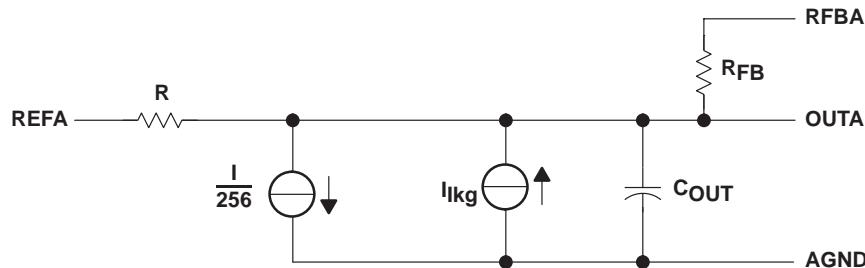


Figure 2. TLC7528 Equivalent Circuit, DACA Latch Loaded With 11111111

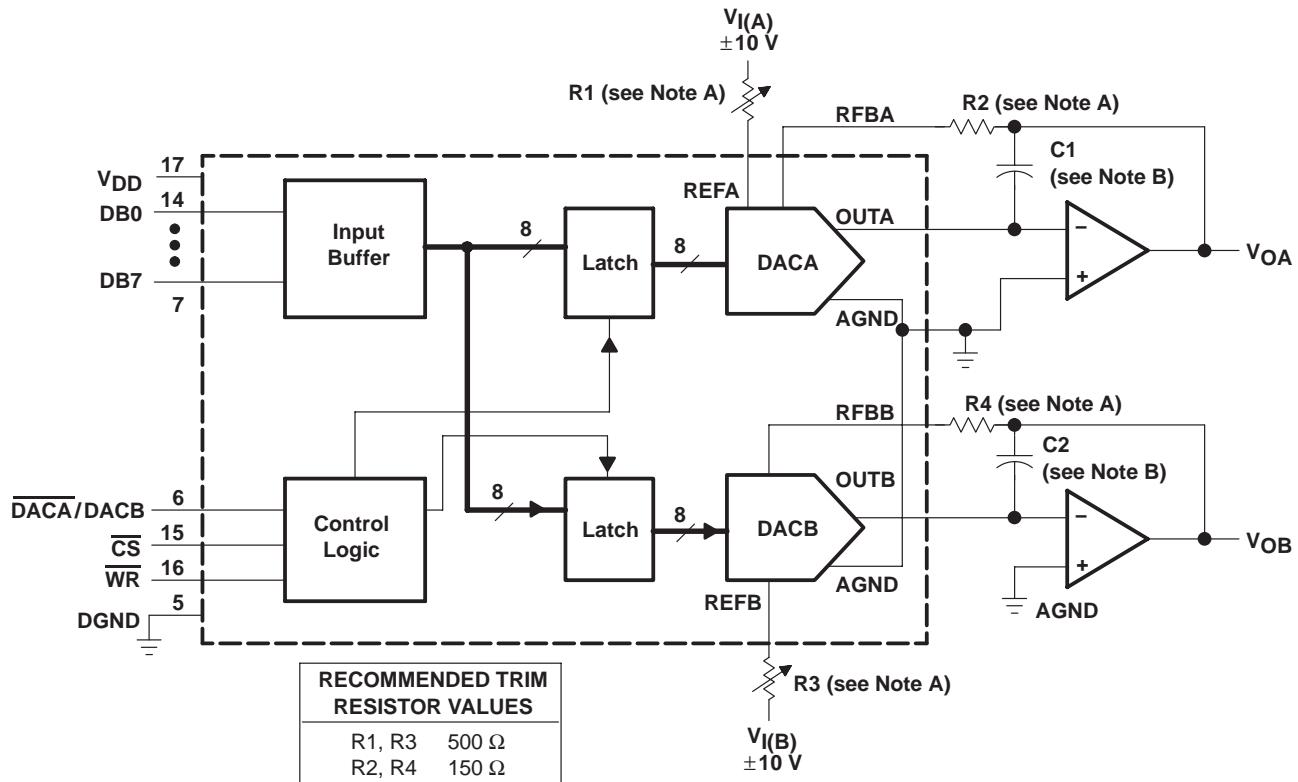
MODE SELECTION TABLE

DACA/DACB	CS	WR	DACA	DACB
L	L	L	Write	Hold
H	L	L	Hold	Write
X	H	X	Hold	Hold
X	X	H	Hold	Hold

L = low level, H = high level, X = don't care

## APPLICATION INFORMATION

These devices are capable of performing 2-quadrant or full 4-quadrant multiplication. Circuit configurations for 2-quadrant and 4-quadrant multiplication are shown in Figure 3 and Figure 4. Table 1 and Table 2 summarize input coding for unipolar and bipolar operation, respectively.



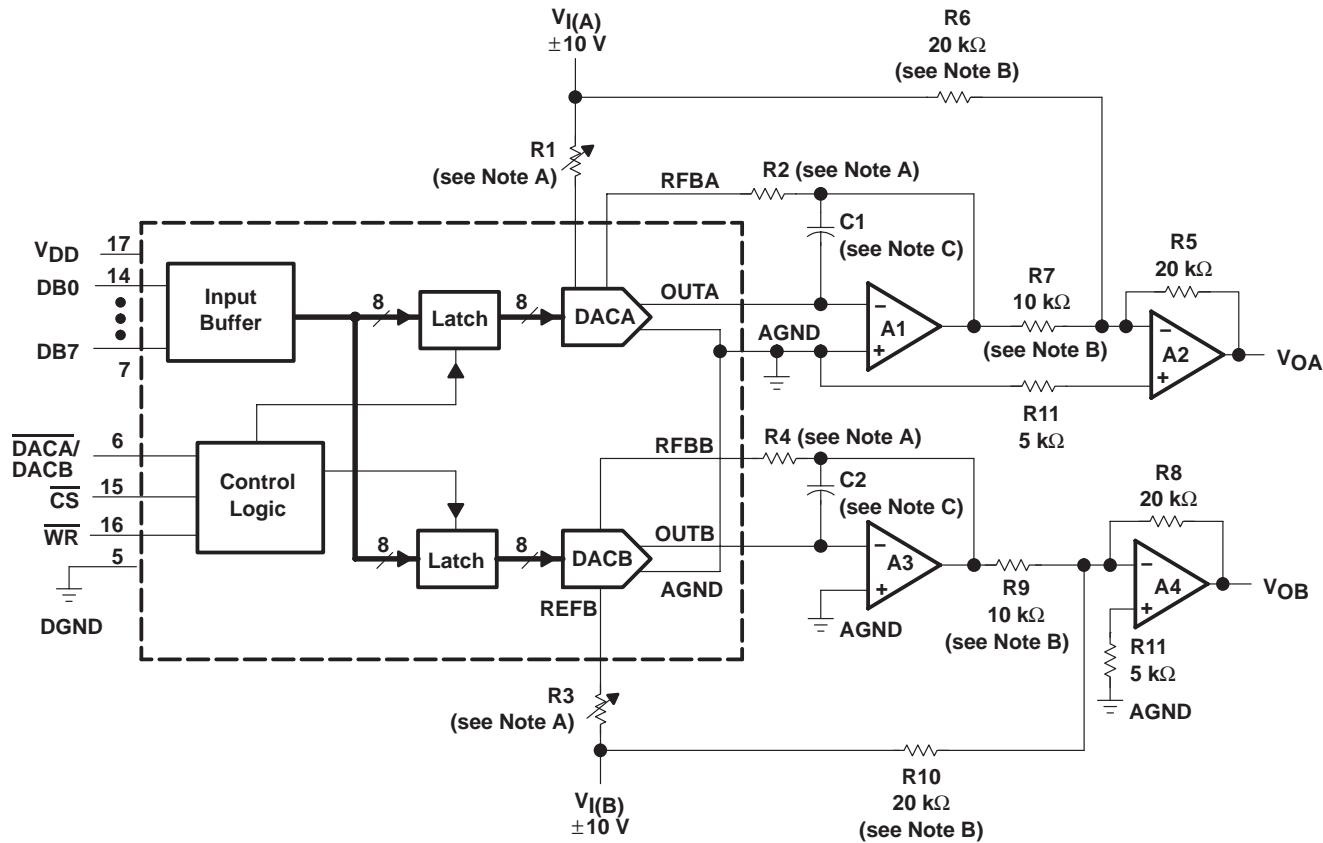
- NOTES:
- A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table for recommended values. Make gain adjustment with digital input of 255.
  - B. C1 and C2 phase compensation capacitors (10pF to 15pF) are required when using high-speed amplifiers to prevent ringing or oscillation.

**Figure 3. Unipolar Operation (2-Quadrant Multiplication)**

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## APPLICATION INFORMATION



- NOTES:
- A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table in Figure 3 for recommended values. Adjust R1 for V<sub>OA</sub> = 0V with code 10000000 in DACA latch. Adjust R3 for V<sub>OB</sub> = 0V with 10000000 in DACB latch.
  - B. Matching and tracking are essential for resistor pairs R6, R7, R9, and R10.
  - C. C1 and C2 phase compensation capacitors (10pF to 15pF) may be required if A1 and A3 are high-speed amplifiers.

Figure 4. Bipolar Operation (4-Quadrant Operation)

Table 1. Unipolar Binary Code

DAC LATCH CONTENTS		ANALOG OUTPUT
MSB	LSB†	
1 1 1 1 1 1 1 1		-V <sub>I</sub> (255/256)
1 0 0 0 0 0 0 1		-V <sub>I</sub> (129/256)
1 0 0 0 0 0 0 0		-V <sub>I</sub> (128/256) = -V <sub>I</sub> /2
0 1 1 1 1 1 1 1		-V <sub>I</sub> (127/256)
0 0 0 0 0 0 0 1		-V <sub>I</sub> (1/256)
0 0 0 0 0 0 0 0		-V <sub>I</sub> (0/256) = 0

†1LSB =  $(2^{-8})V_I$

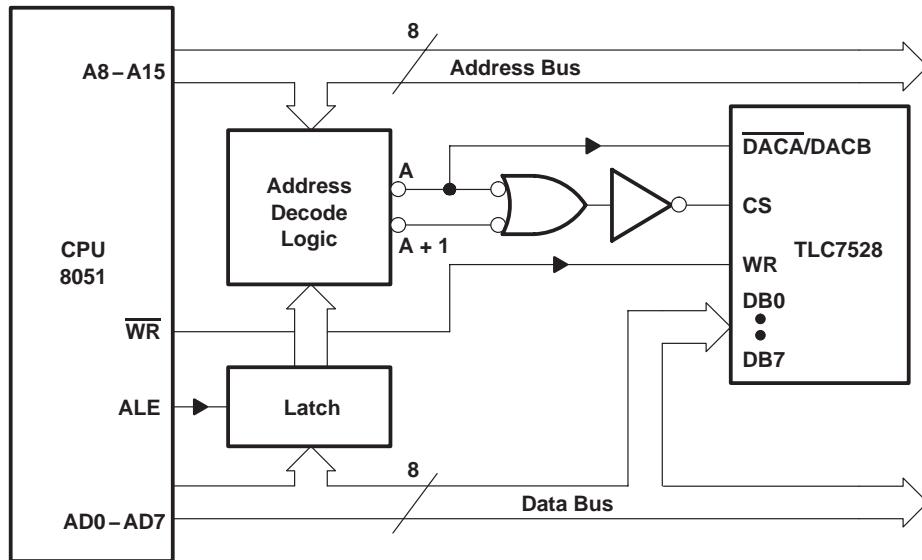
Table 2. Bipolar (Offset Binary) Code

DAC LATCH CONTENTS		ANALOG OUTPUT
MSB	LSB‡	
1 1 1 1 1 1 1 1		V <sub>I</sub> (127/128)
1 0 0 0 0 0 0 1		V <sub>I</sub> (1/128)
1 0 0 0 0 0 0 0		0V
0 1 1 1 1 1 1 1		-V <sub>I</sub> (1/128)
0 0 0 0 0 0 0 1		-V <sub>I</sub> (127/128)
0 0 0 0 0 0 0 0		-V <sub>I</sub> (128/128)

‡1LSB =  $(2^{-7})V_I$

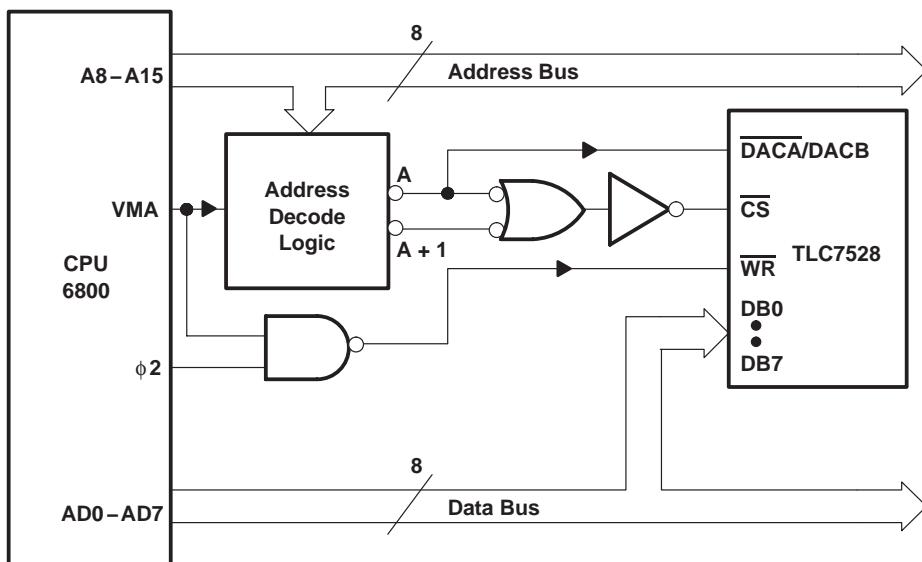
## APPLICATION INFORMATION

### microprocessor interface information



NOTE A: A = decoded address for TLC7528 DACA  
 A + 1 = decoded address for TLC7528 DACB

**Figure 5. TLC7528: Intel 8051 Interface**



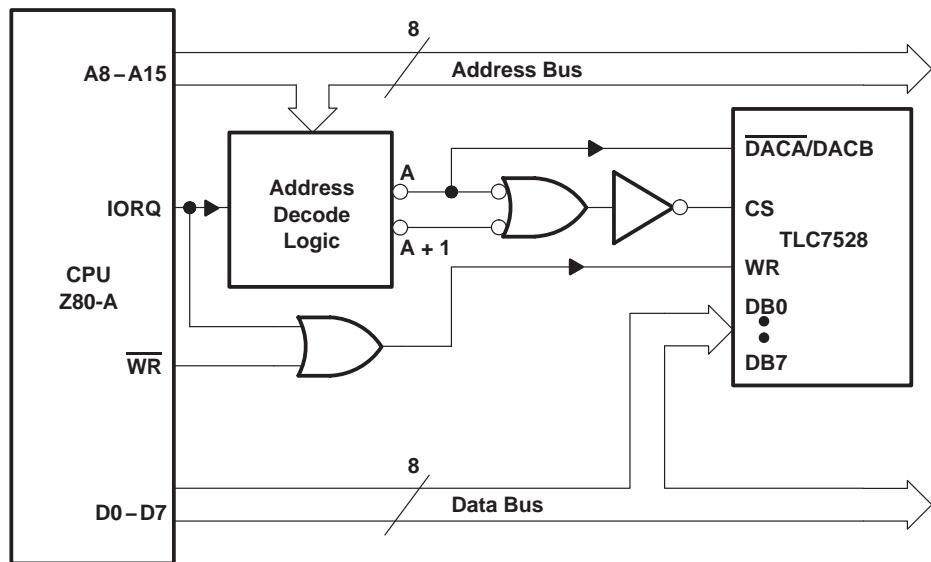
NOTE A: A = decoded address for TLC7528 DACA  
 A + 1 = decoded address for TLC7528 DACB

**Figure 6. TLC7528: 6800 Interface**

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**APPLICATION INFORMATION**



NOTE A: A = decoded address for TLC7528 DACA  
A + 1 = decoded address for TLC7528 DACB

**Figure 7. TLC7528 To Z-80A Interface**

**programmable window detector**

The programmable window comparator shown in Figure 8 determines if the voltage applied to the DAC feedback resistors is within the limits programmed into the data latches of these devices. Input signal range depends on the reference and polarity; that is, the test input range is 0 to  $-V_{ref}$ . The DACA and DACB data latches are programmed with the upper and lower test limits. A signal within the programmed limits drives the output high.

## APPLICATION INFORMATION

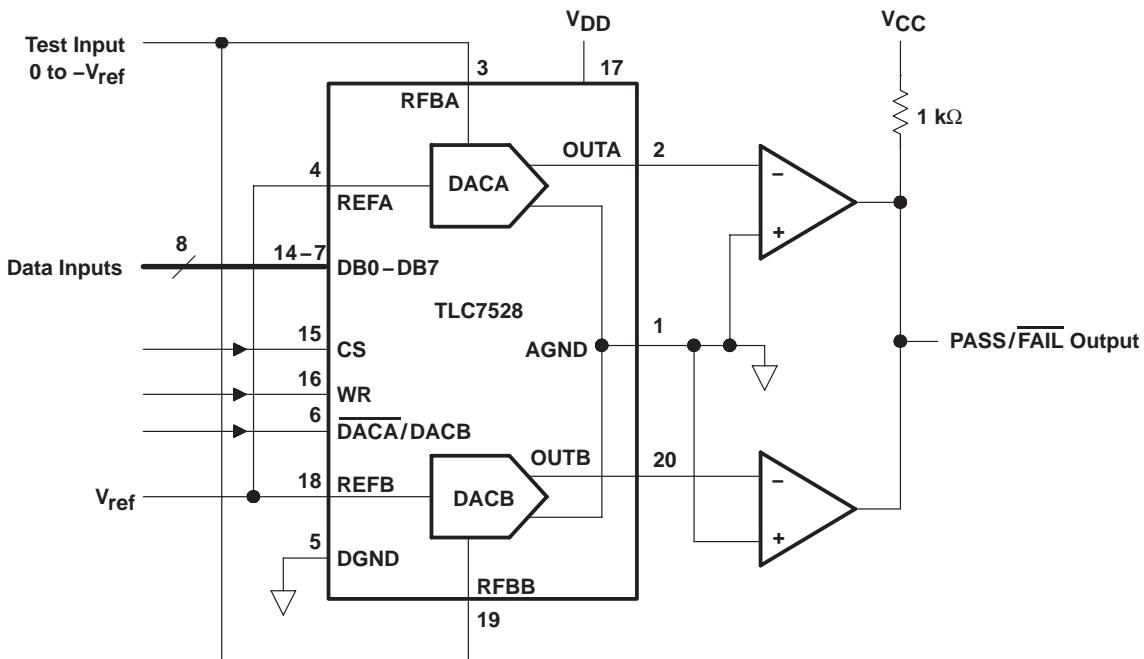


Figure 8. Digitally-Programmable Window Comparator (Upper- and Lower-Limit Tester)

### digitally-controlled signal attenuator

Figure 9 shows a TLC7528 configured as a two-channel programmable attenuator. Applications include stereo audio and telephone signal level control. Table 3 shows input codes vs attenuation for a 0dB to 15.5dB range.

$$\text{Attenuation dB} = -20 \log_{10} D/256, D = \text{digital input code}$$

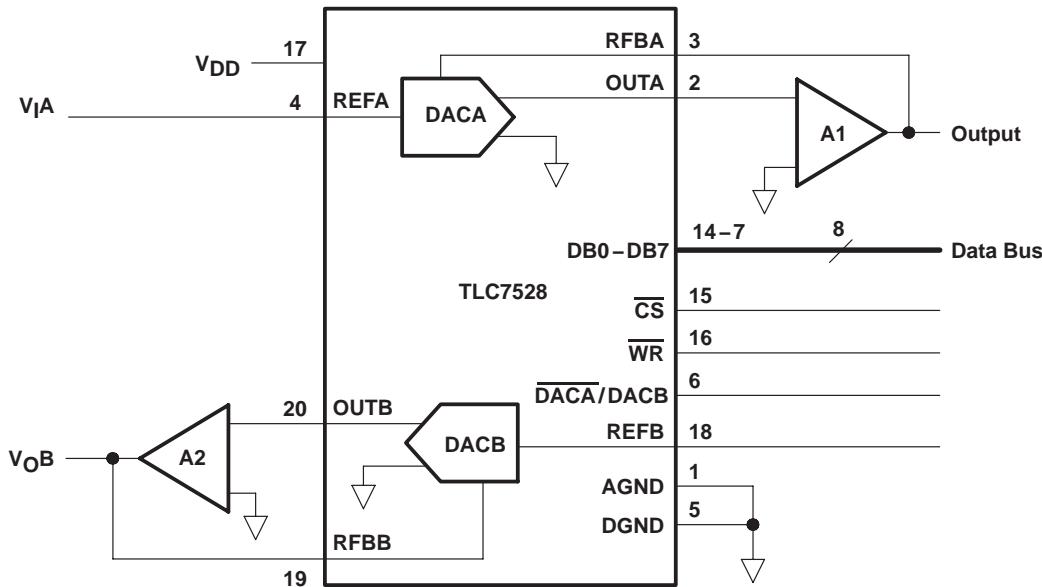


Figure 9. Digitally Controlled Dual Telephone Attenuator

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**APPLICATION INFORMATION**

**Table 3. Attenuation vs DACA, DACB Code**

ATTEN (dB)	DAC INPUT CODE	CODE IN DECIMAL	ATTN (dB)	DAC INPUT CODE	CODE IN DECIMAL
0	11111111	255	8.0	01100110	102
0.5	11110010	242	8.5	01100000	96
1.0	11100100	228	9.0	01011011	91
1.5	11010111	215	9.5	01010110	86
2.0	11001011	203	10.0	01010001	81
2.5	11000000	192	10.5	01001100	76
3.0	10110101	181	11.0	01001000	72
3.5	10101011	171	11.5	01000100	68
4.0	10100010	162	12.0	01000000	64
4.5	10011000	152	12.5	00111101	61
5.0	10011111	144	13.0	00111001	57
5.5	10001000	136	13.5	00110110	54
6.0	10000000	128	14.0	00110011	51
6.5	01111001	121	14.5	00110000	48
7.0	01110010	114	15.0	00101110	46
7.5	01101100	108	15.5	00101011	43

**programmable state-variable filter**

This programmable state-variable or universal filter configuration provides low-pass, high-pass, and bandpass outputs, and is suitable for applications requiring microprocessor control of filter parameters.

As shown in Figure 10, DACA1 and DACB1 control the gain and Q of the filter while DACA2 and DACB2 control the cutoff frequency. Both halves of the DACA2 and DACB2 must track accurately in order for the cutoff-frequency equation to be true. With the TLC7528, this validity is easy to achieve.

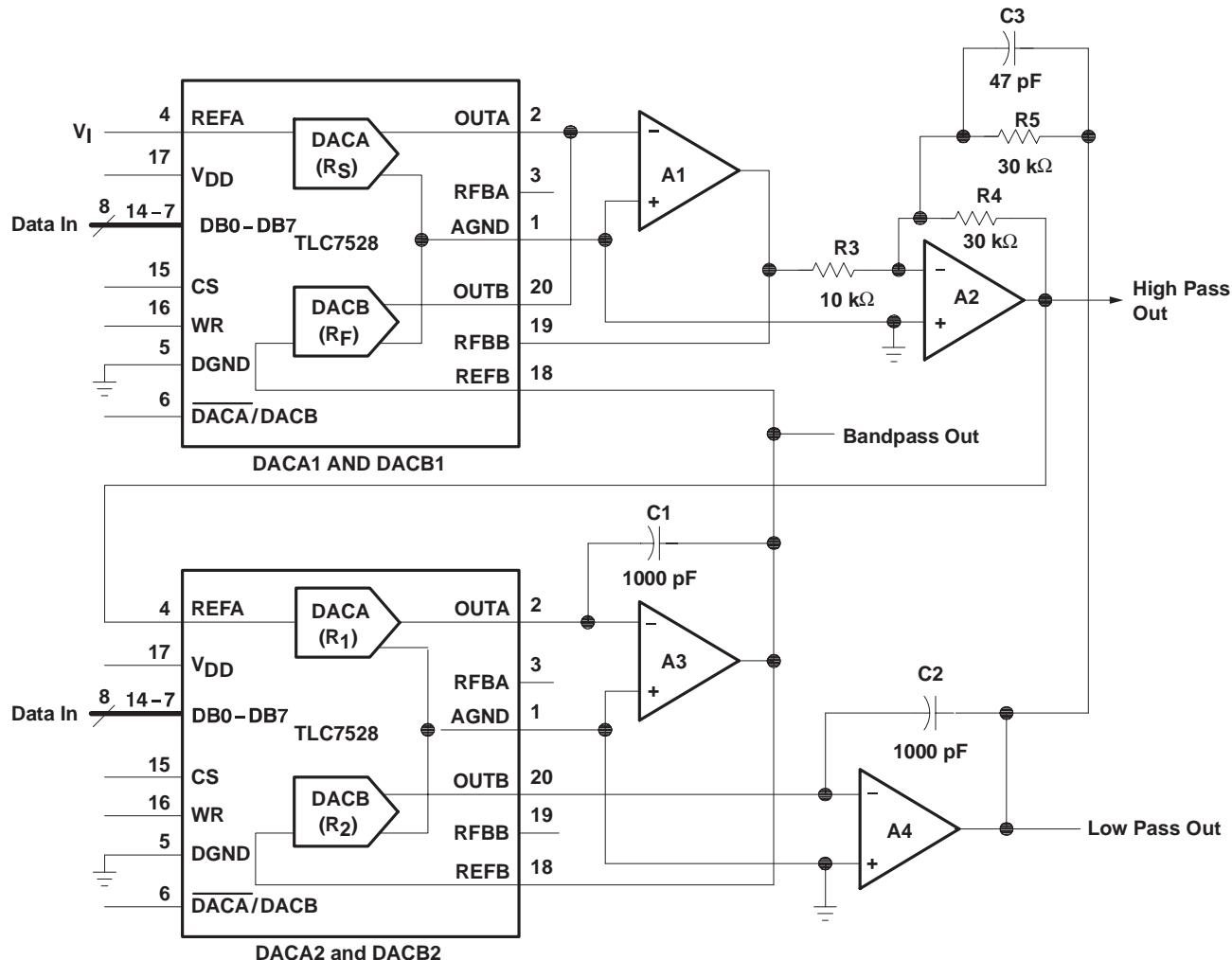
$$f_C = \frac{1}{2\pi R_1 C_1}$$

The programmable range for the cutoff or center frequency is 0kHz to 15kHz with a Q ranging from 0.3 to 4.5. This parameter defines the limits of the component values.



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## APPLICATION INFORMATION



**Circuit Equations:**

$$C_1 = C_2, R_1 = R_2, R_4 = R_5$$

$$Q = \frac{R_3}{R_4} \times \frac{R_F}{R_{fb}(\text{DACB1})}$$

Where:

$R_{fb}$  is the internal resistor connected between OUTB and RFBB

$$G = -\frac{R_F}{R_S}$$

- NOTES: A. Op-amps A1, A2, A3, and A4 are TL287.  
 B. CS compensates for the op-amp gain-bandwidth limitations.  
 C. DAC equivalent resistance equals  $\frac{256 \times (\text{DAC ladder resistance})}{\text{DAC digital code}}$

**Figure 10. Digitally-Controlled State-Variable Filter**

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## APPLICATION INFORMATION

### voltage-mode operation

It is possible to operate the current multiplying D/A converter of these devices in a voltage mode. In the voltage mode, a fixed voltage is placed on the current output terminal. The analog output voltage is then available at the reference voltage terminal. Figure 11 is an example of a current multiplying D/A that operates in the voltage mode.

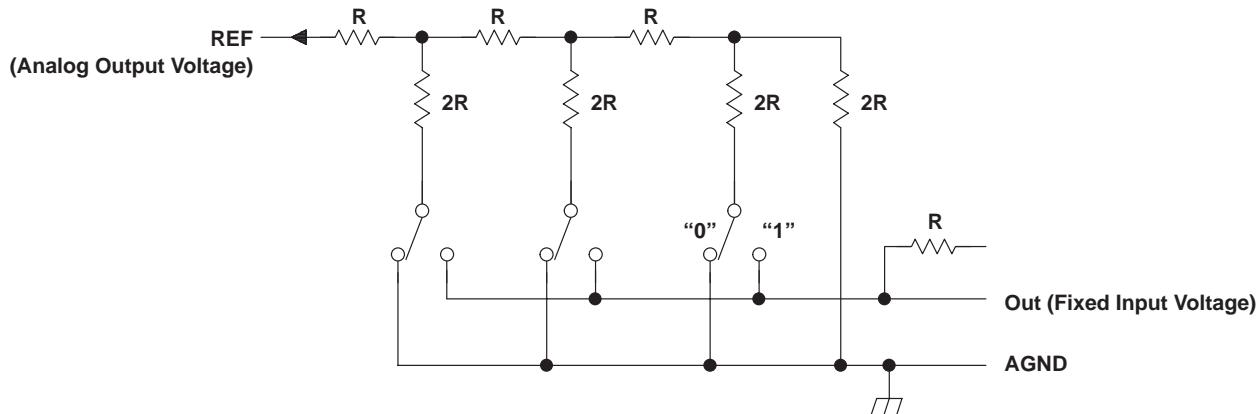


Figure 11. Voltage-Mode Operation

The following equation shows the relationship between the fixed input voltage and the analog output voltage:

$$V_O = V_I (D/256)$$

Where:

$V_O$  = analog output voltage

$V_I$  = fixed input voltage (must not be forced below 0V.)

D = digital input code converted to decimal

In voltage-mode operation, these devices meet the following specification:

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Linearity error at REFA or REFB	$V_{DD} = 5V$ , OUTA or OUTB at 2.5V, $T_A = +25^\circ C$	1		LSB

## Revision History

DATE	REV	PAGE	SECTION	DESCRIPTION
11/08	E	13	Application Information	Corrected Figure 10.
6/07	D	Front Page	—	Deleted Available Options table.
		3	—	Inserted Package/Ordering information.

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TLC7528CDW</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C
TLC7528CDW.A	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C
TLC7528CDW.B	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528C
<a href="#">TLC7528CDWR</a>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C
TLC7528CDWR.A	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C
TLC7528CDWR.B	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528C
TLC7528CDWRG4	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C
<a href="#">TLC7528CFN</a>	Obsolete	Production	PLCC (FN)   20	-	-	Call TI	Call TI	0 to 70	TLC7528C
<a href="#">TLC7528CFNR</a>	Obsolete	Production	PLCC (FN)   20	-	-	Call TI	Call TI	0 to 70	TLC7528C
<a href="#">TLC7528CN</a>	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLC7528CN
TLC7528CN.A	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLC7528CN
<a href="#">TLC7528CNS</a>	Active	Production	SOP (NS)   20	40   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528
TLC7528CNS.A	Active	Production	SOP (NS)   20	40   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528
<a href="#">TLC7528CNSR</a>	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528
TLC7528CNSR.A	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528
<a href="#">TLC7528CPW</a>	Active	Production	TSSOP (PW)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C
TLC7528CPW.A	Active	Production	TSSOP (PW)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C
<a href="#">TLC7528CPWR</a>	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C
TLC7528CPWR.A	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C
TLC7528CPWR.B	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528C
<a href="#">TLC7528EDW</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528E
TLC7528EDW.A	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528E
TLC7528EDWG4	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528E
<a href="#">TLC7528EDWR</a>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528E
TLC7528EDWR.A	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528E
TLC7528EDWR.B	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528E
<a href="#">TLC7528EN</a>	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	TLC7528EN
TLC7528EN.A	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	TLC7528EN
<a href="#">TLC7528IDW</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLC7528IDW.A	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I
TLC7528IDW.B	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528I
<b>TLC7528IDWR</b>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I
TLC7528IDWR.A	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I
TLC7528IDWR.B	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528I
<b>TLC7528IFN</b>	Obsolete	Production	PLCC (FN)   20	-	-	Call TI	Call TI	-25 to 85	TLC7528I
<b>TLC7528IN</b>	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	-25 to 85	TLC7528IN
TLC7528IN.A	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	-25 to 85	TLC7528IN
<b>TLC7528IPW</b>	Active	Production	TSSOP (PW)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I
TLC7528IPW.A	Active	Production	TSSOP (PW)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I
<b>TLC7528IPWR</b>	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I
TLC7528IPWR.A	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I
TLC7528IPWR.B	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528I

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

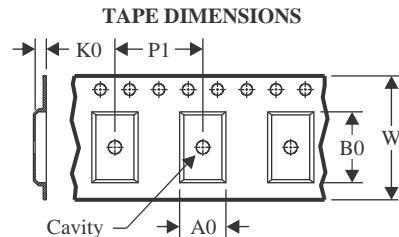
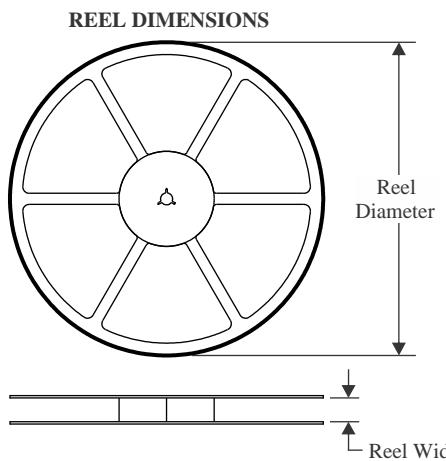
<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

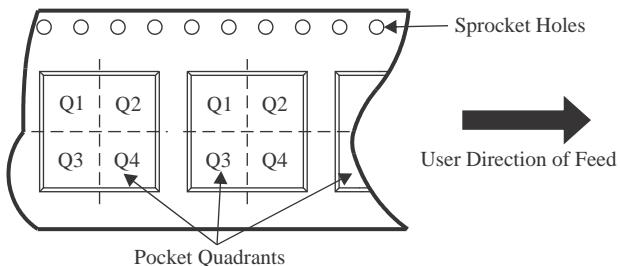
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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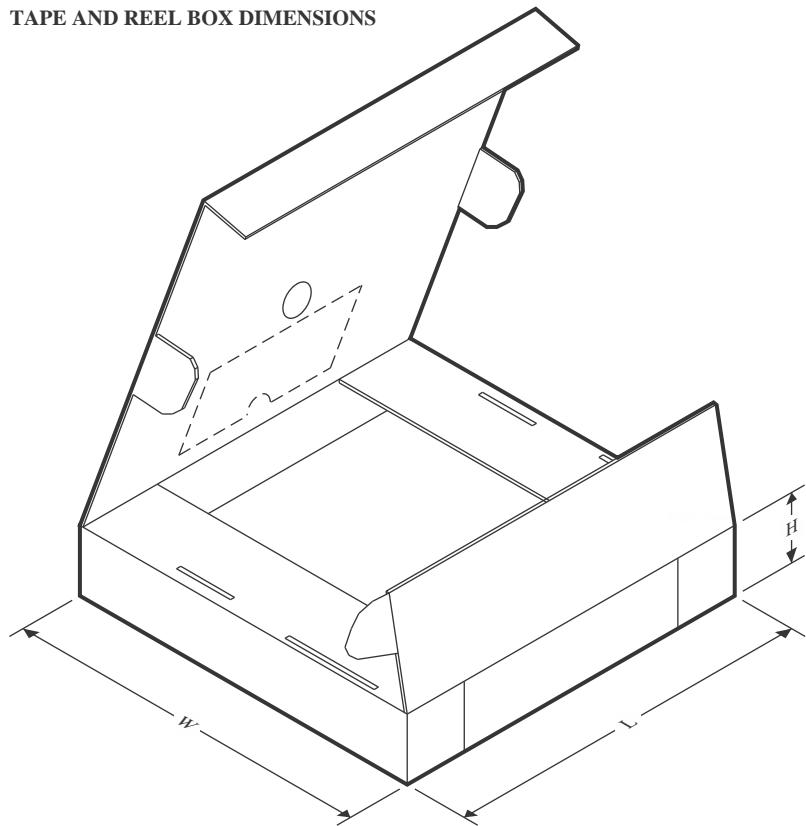
**TAPE AND REEL INFORMATION**

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**

\*All dimensions are nominal

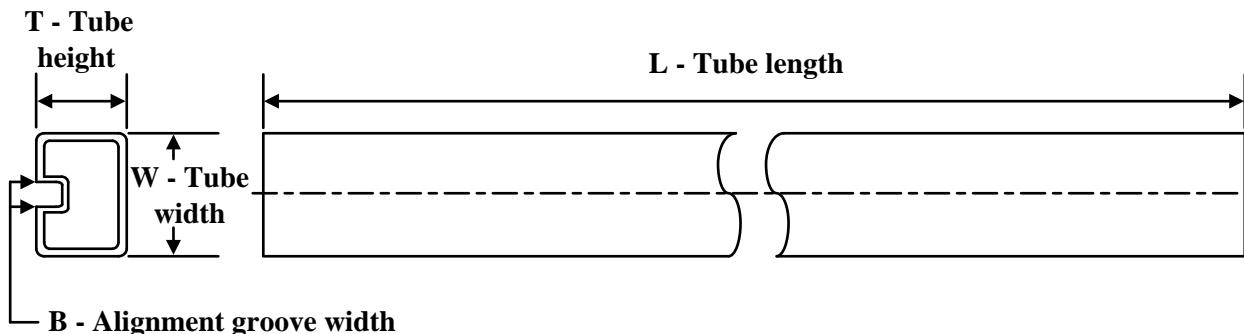
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC7528CDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
TLC7528CNSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
TLC7528CPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
TLC7528EDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
TLC7528IDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
TLC7528IPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC7528CDWR	SOIC	DW	20	2000	356.0	356.0	45.0
TLC7528CNSR	SOP	NS	20	2000	356.0	356.0	45.0
TLC7528CPWR	TSSOP	PW	20	2000	353.0	353.0	32.0
TLC7528EDWR	SOIC	DW	20	2000	356.0	356.0	45.0
TLC7528IDWR	SOIC	DW	20	2000	356.0	356.0	45.0
TLC7528IPWR	TSSOP	PW	20	2000	353.0	353.0	32.0

## TUBE



\*All dimensions are nominal

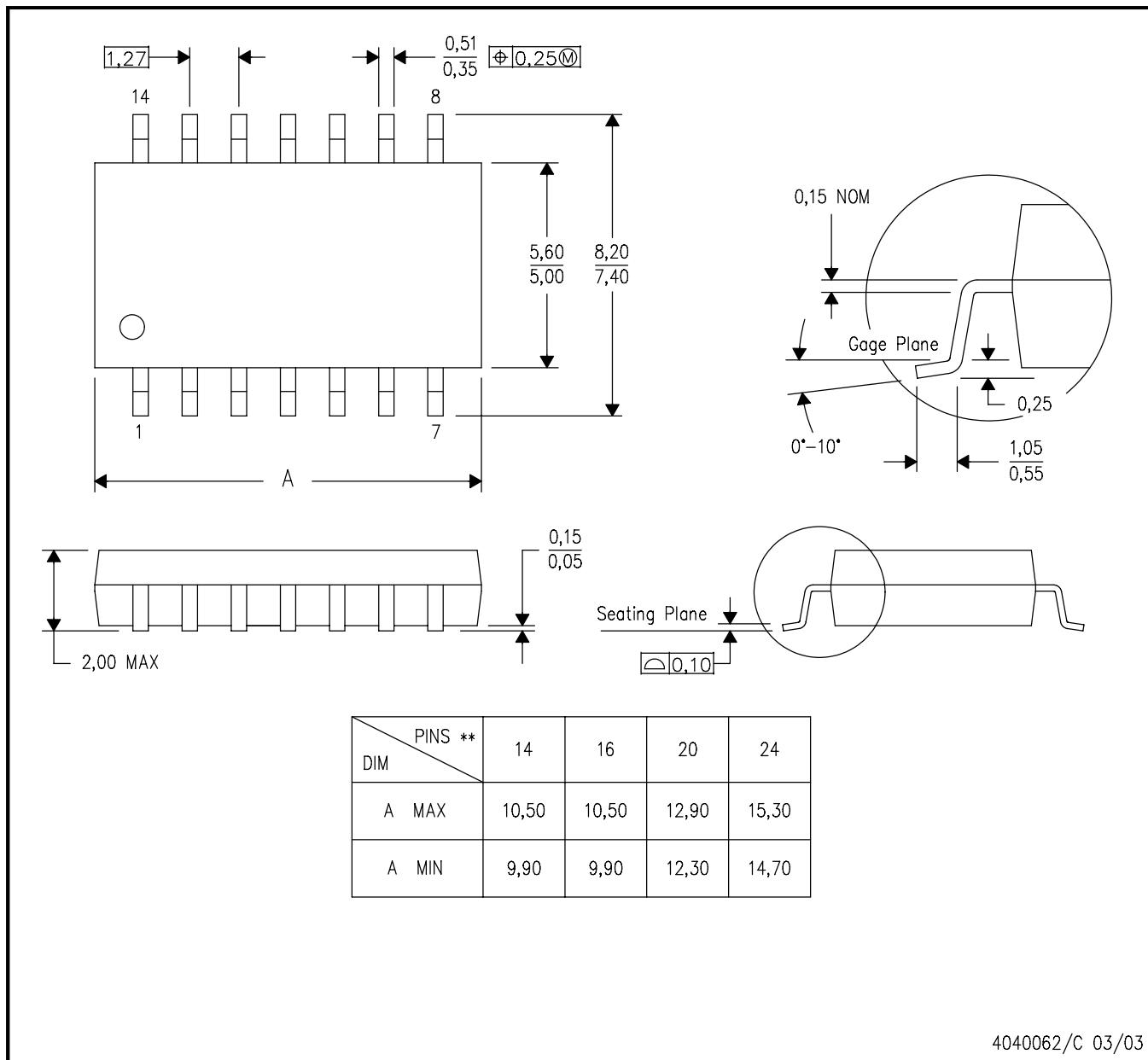
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T ( $\mu$ m)	B (mm)
TLC7528CDW	DW	SOIC	20	25	507	12.83	5080	6.6
TLC7528CDW.A	DW	SOIC	20	25	507	12.83	5080	6.6
TLC7528CDW.B	DW	SOIC	20	25	507	12.83	5080	6.6
TLC7528CN	N	PDIP	20	20	506	13.97	11230	4.32
TLC7528CN.A	N	PDIP	20	20	506	13.97	11230	4.32
TLC7528CNS	NS	SOP	20	40	530	10.5	4000	4.1
TLC7528CNS.A	NS	SOP	20	40	530	10.5	4000	4.1
TLC7528CPW	PW	TSSOP	20	70	530	10.2	3600	3.5
TLC7528CPW.A	PW	TSSOP	20	70	530	10.2	3600	3.5
TLC7528EDW	DW	SOIC	20	25	507	12.83	5080	6.6
TLC7528EDW.A	DW	SOIC	20	25	507	12.83	5080	6.6
TLC7528EDWG4	DW	SOIC	20	25	507	12.83	5080	6.6
TLC7528EN	N	PDIP	20	20	506	13.97	11230	4.32
TLC7528EN.A	N	PDIP	20	20	506	13.97	11230	4.32
TLC7528IDW	DW	SOIC	20	25	507	12.83	5080	6.6
TLC7528IDW.A	DW	SOIC	20	25	507	12.83	5080	6.6
TLC7528IDW.B	DW	SOIC	20	25	507	12.83	5080	6.6
TLC7528IN	N	PDIP	20	20	506	13.97	11230	4.32
TLC7528IN.A	N	PDIP	20	20	506	13.97	11230	4.32
TLC7528IPW	PW	TSSOP	20	70	530	10.2	3600	3.5
TLC7528IPW.A	PW	TSSOP	20	70	530	10.2	3600	3.5

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

**14-PINS SHOWN**

**PLASTIC SMALL-OUTLINE PACKAGE**



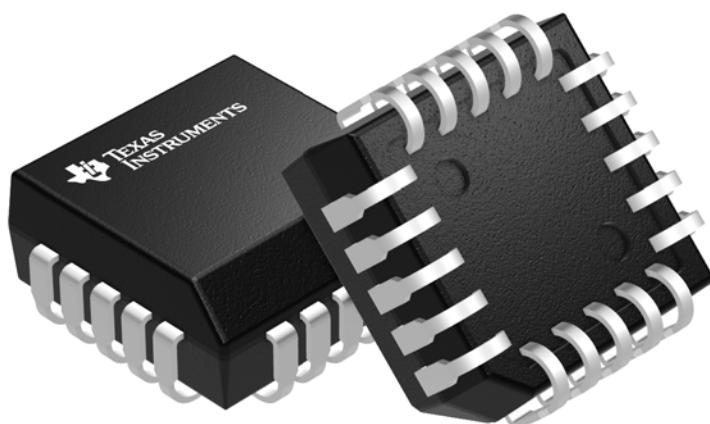
- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## GENERIC PACKAGE VIEW

**FN 20**

**PLCC - 4.57 mm max height**

PLASTIC CHIP CARRIER



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040005-2/C

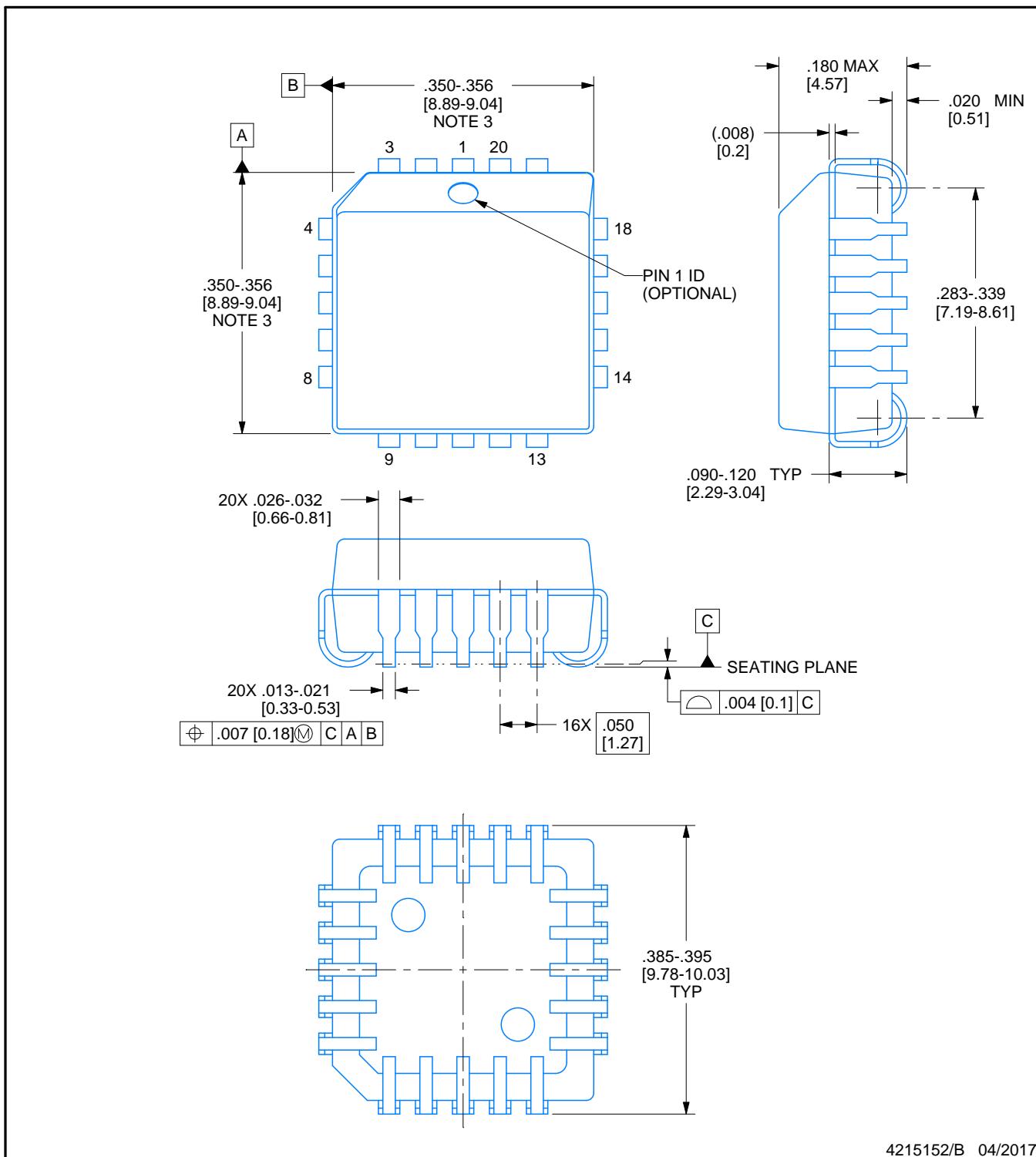
# PACKAGE OUTLINE

**FN0020A**



**PLCC - 4.57 mm max height**

PLASTIC CHIP CARRIER



**NOTES:**

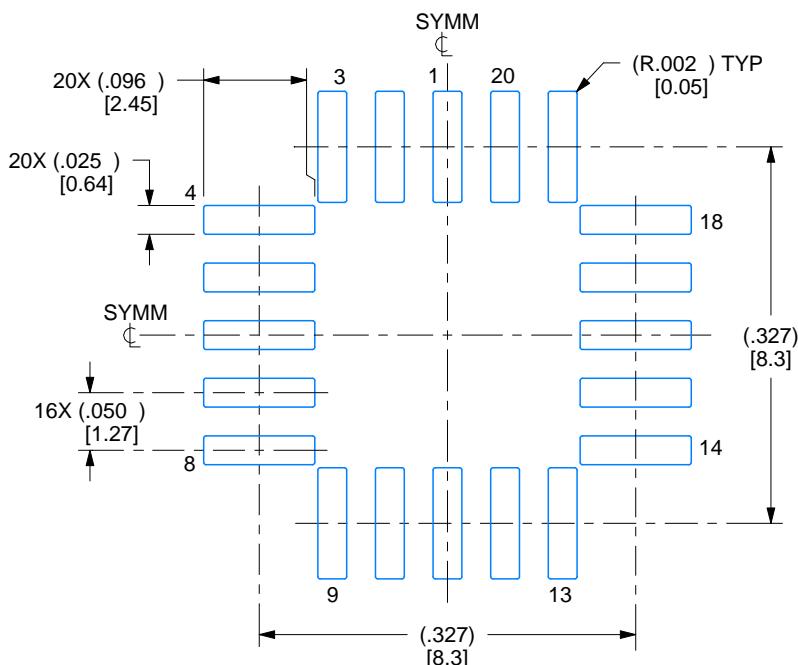
- All linear dimensions are in inches. Any dimensions in brackets are in millimeters. Any dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- Dimension does not include mold protrusion. Maximum allowable mold protrusion .01 in [0.25 mm] per side.
- Reference JEDEC registration MS-018.

# EXAMPLE BOARD LAYOUT

FN0020A

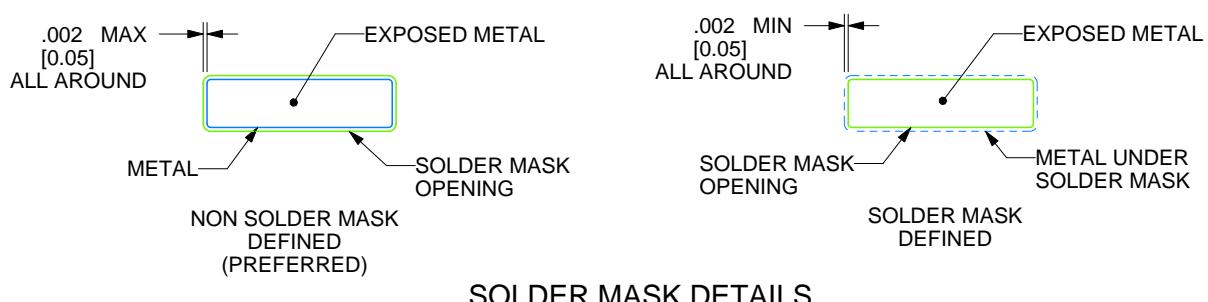
PLCC - 4.57 mm max height

PLASTIC CHIP CARRIER



## LAND PATTERN EXAMPLE

EXPOSED METAL SHOWN  
SCALE:6X



## SOLDER MASK DETAILS

4215152/B 04/2017

NOTES: (continued)

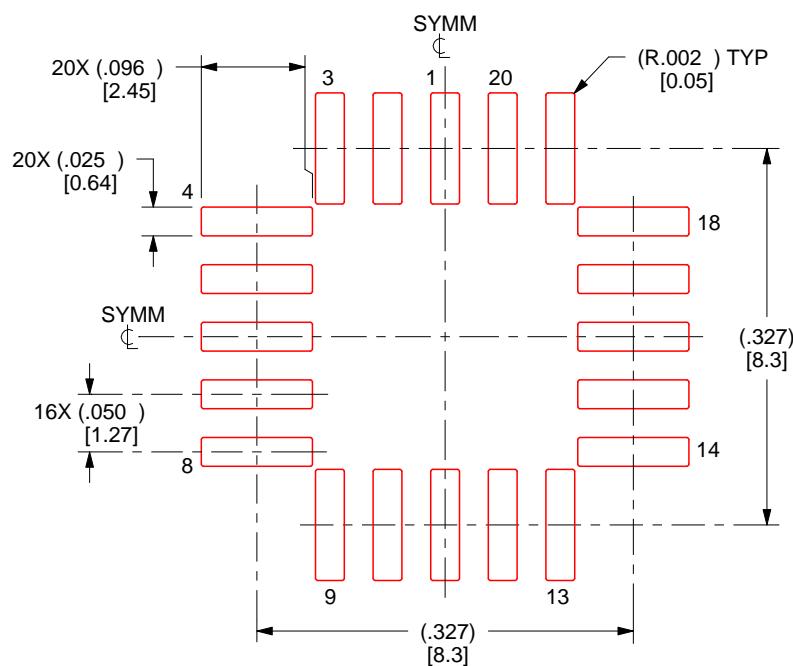
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

**FN0020A**

**PLCC - 4.57 mm max height**

PLASTIC CHIP CARRIER



**SOLDER PASTE EXAMPLE**  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4215152/B 04/2017

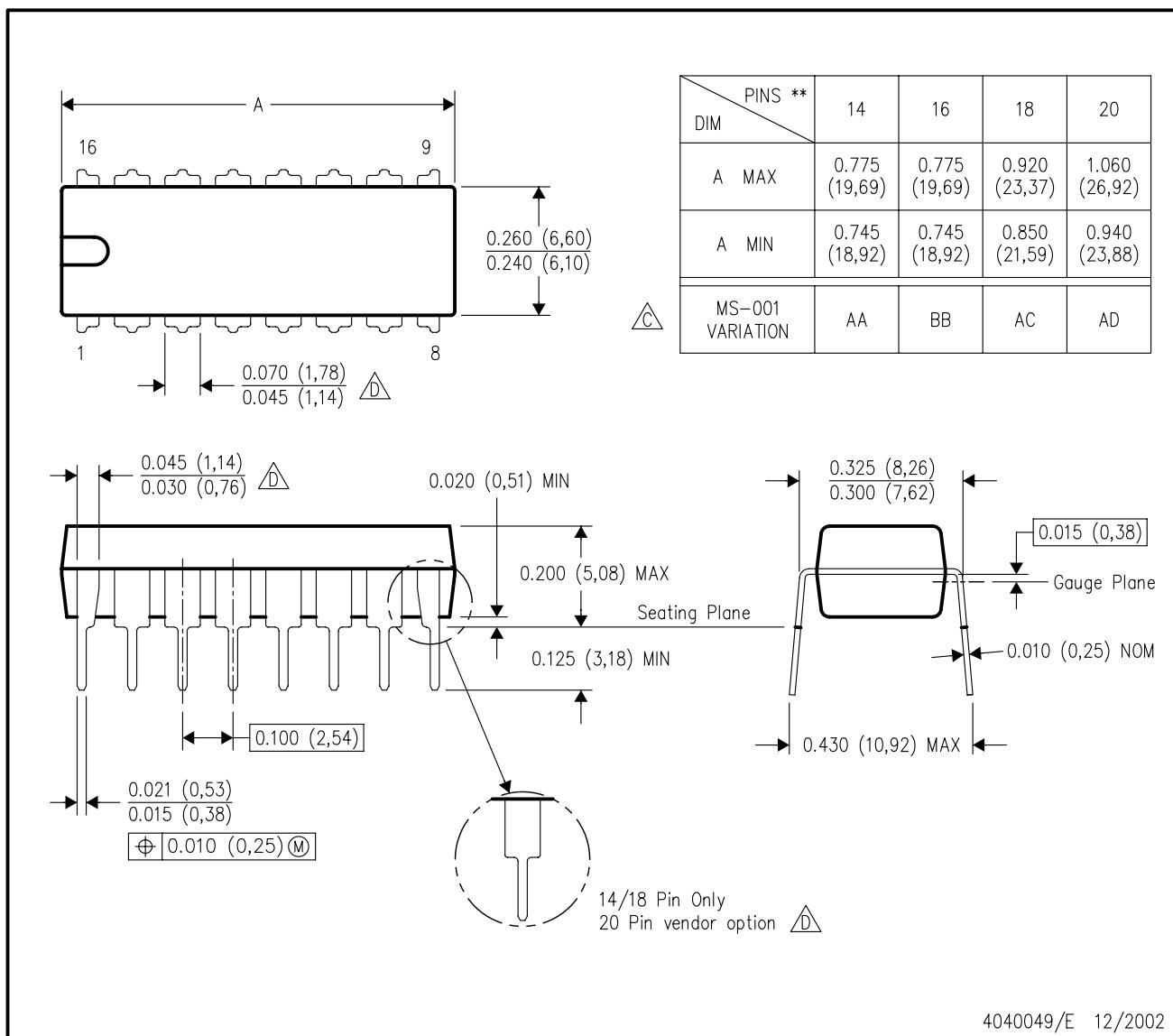
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.

Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

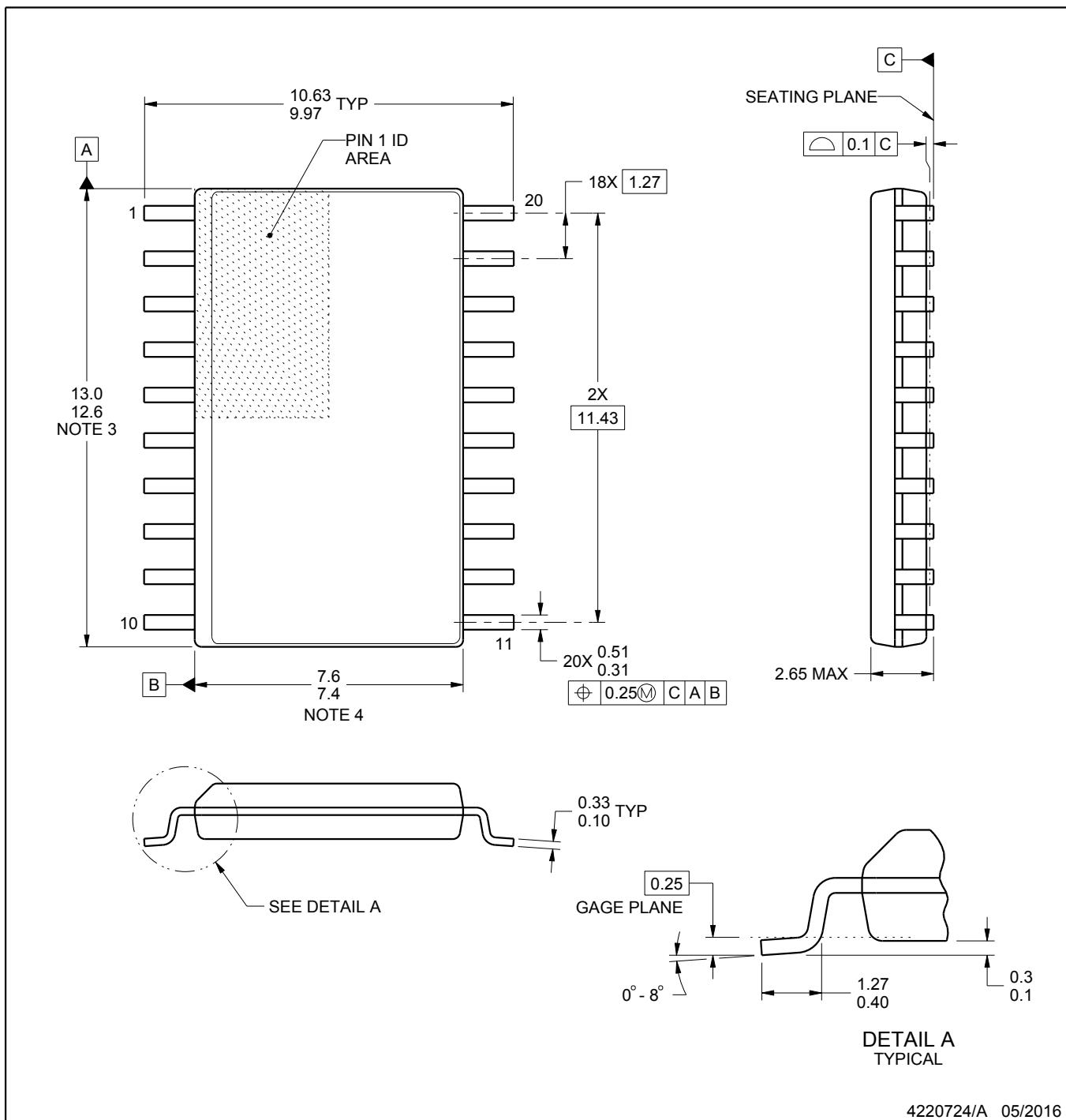
# PACKAGE OUTLINE

DW0020A



SOIC - 2.65 mm max height

SOIC



## NOTES:

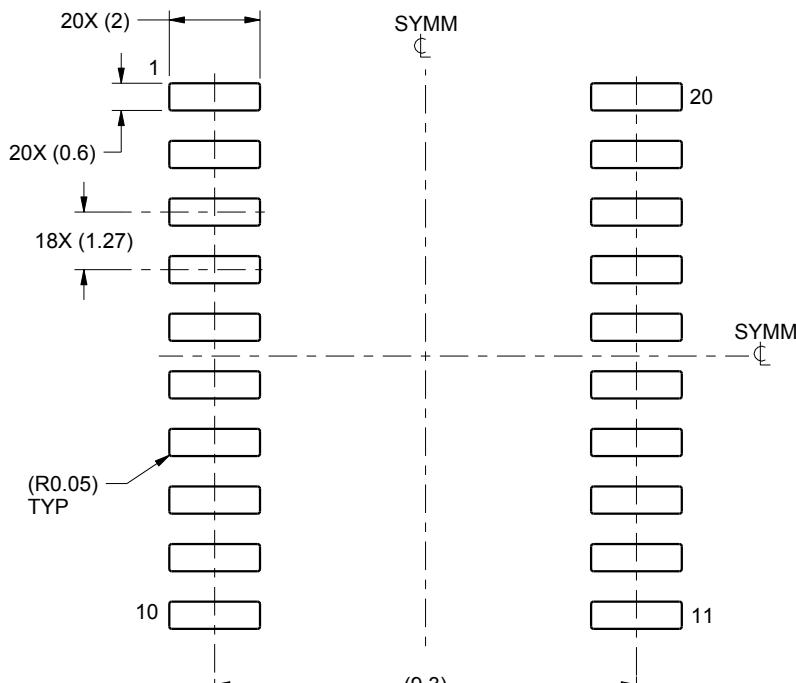
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

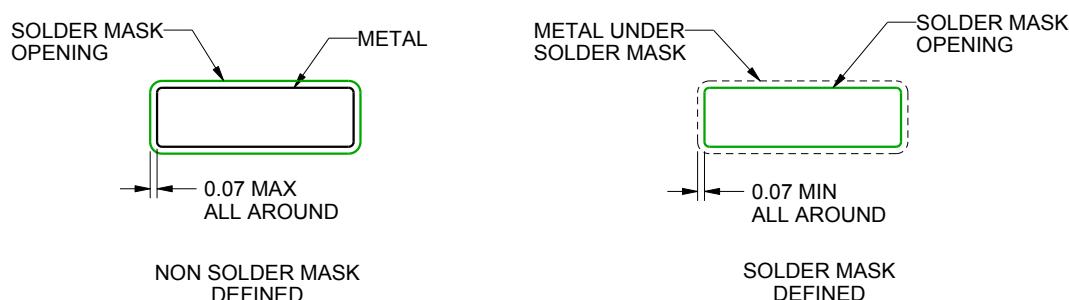
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

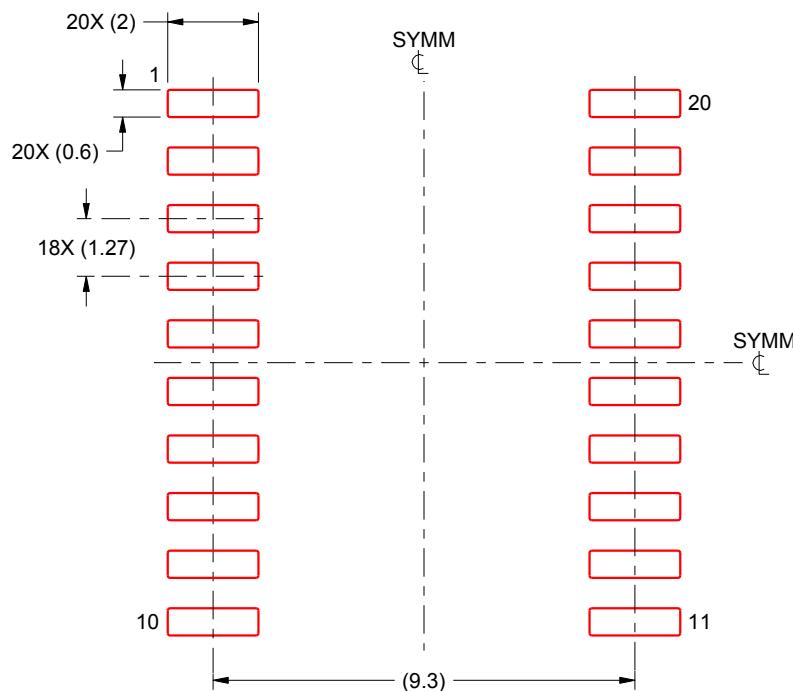
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

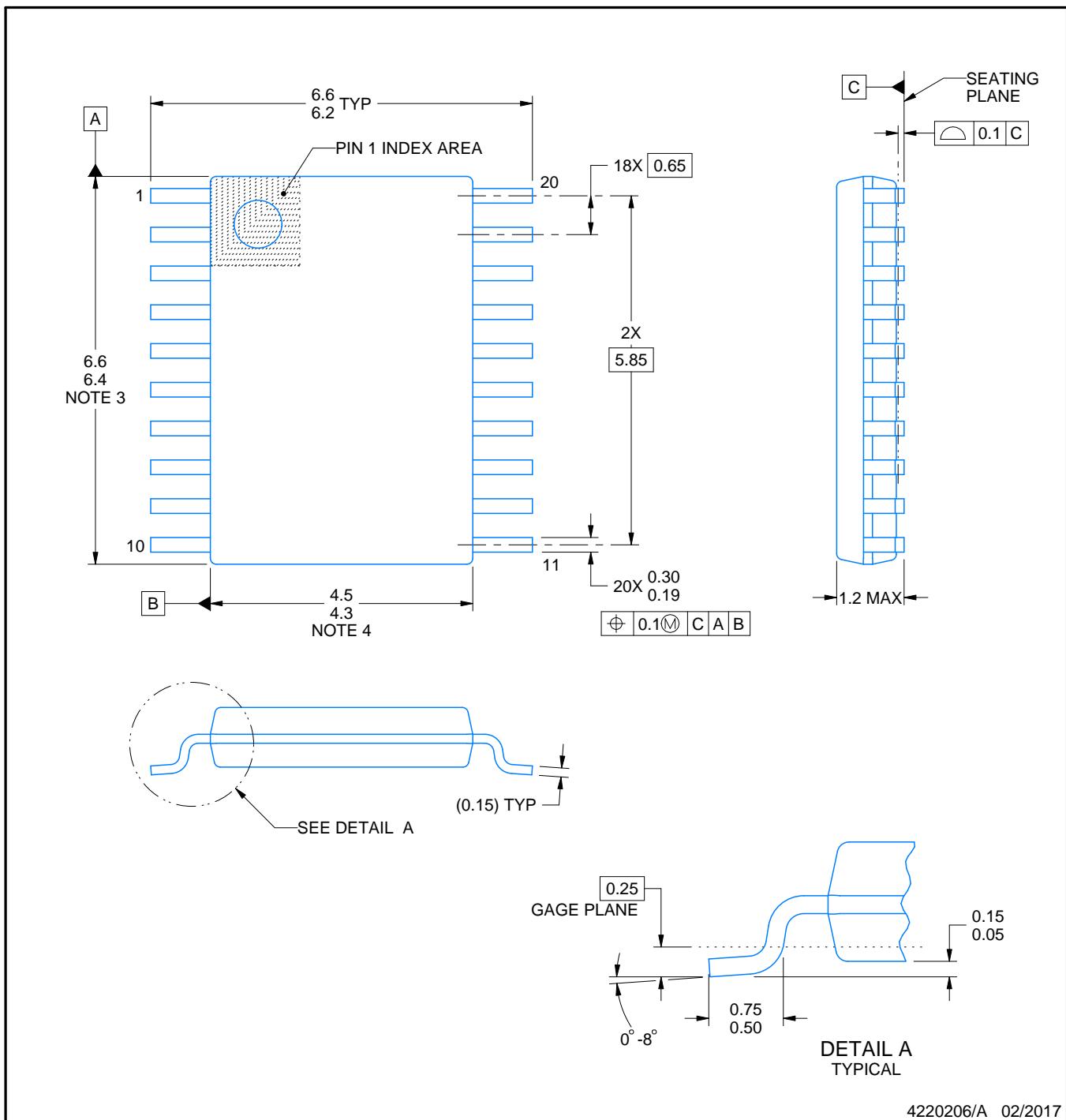
# PACKAGE OUTLINE

PW0020A



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



## NOTES:

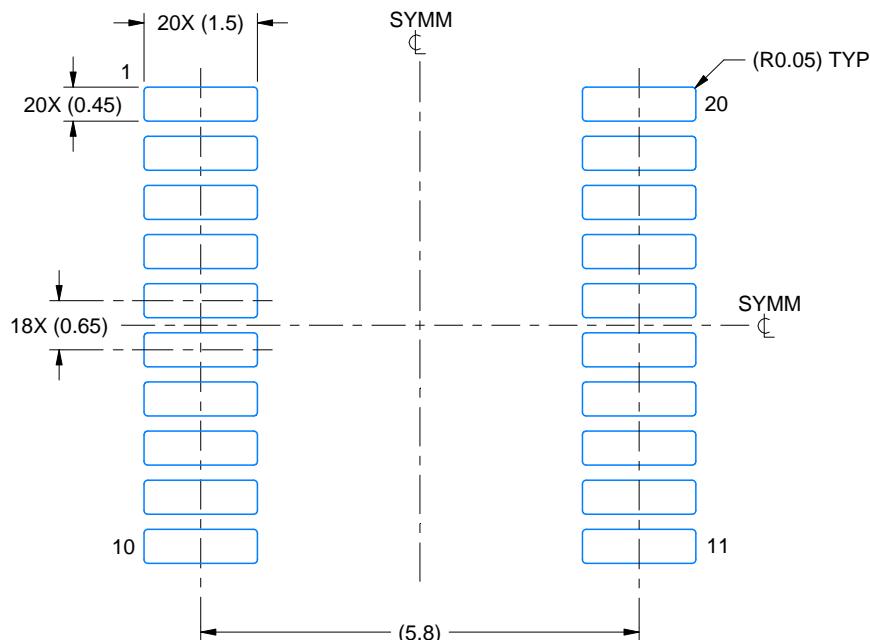
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

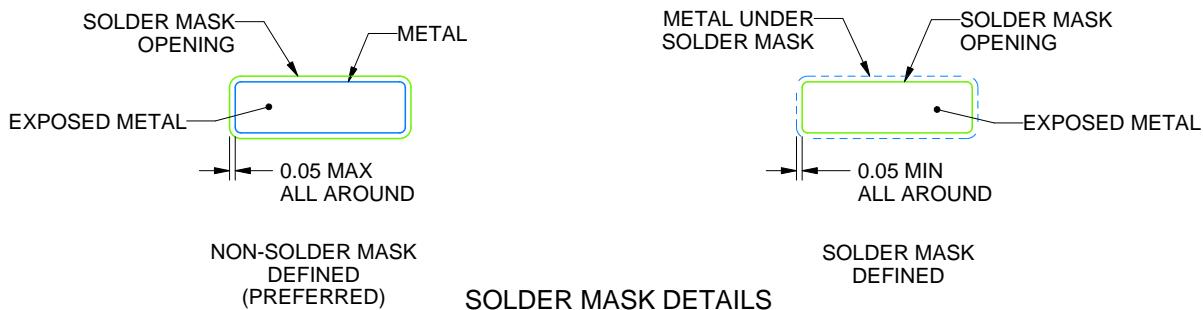
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

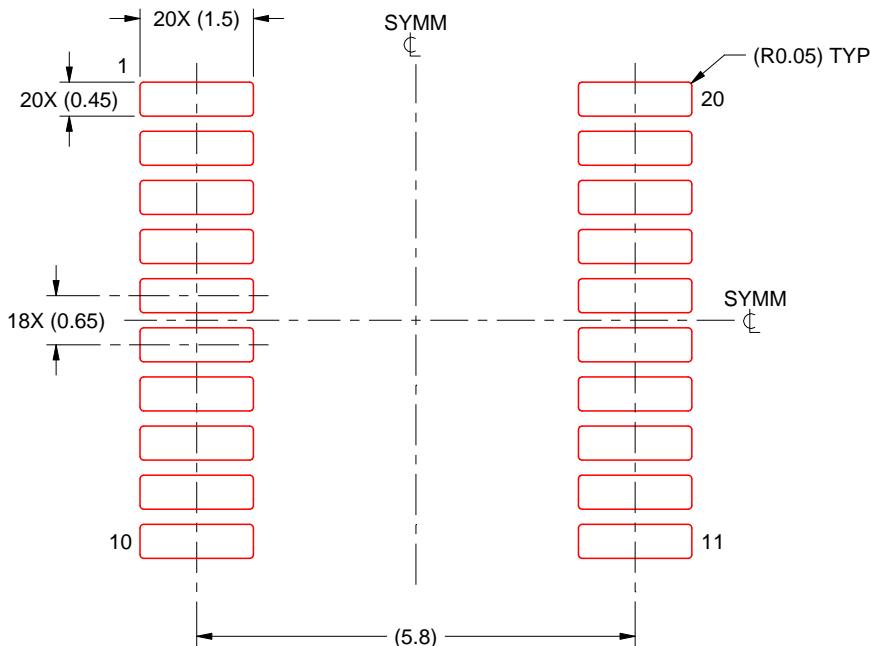
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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